HESSE MECHATRONICS

Workbench 2.0

The Bonding Experts.
Workbench 2.0

Wire Bonder Server for PBS & PiQC

The Workbench 2.0 software is the graphical user interface for the PBS server and enables the display and evaluation of process data.

The PBS server (Windows™ based system) links up to 20 Hesse Mechatronics wire bonders together. The machines can be supervised and administrated while production is running. PBS provides perfect integration of the wire bonders into the production system.

Workbench 2.0 receives and visualizes process data from various sources (quality data from the PiQC database, process data and files from PBS). All data is exported to popular formats for further processing. The Workbench enables file transfer in order to transmit bond programs and parameters from machine to machine.

Advanced features and process advantages

- **Line management**
  Display of all bonders with current status, characteristics and material consumption indicator (e.g. replace wire spool, wedge change etc.)

- **User management**
  Create, change, delete user accounts. Assignment of user accounts to individual wire bonders or production lines

- **File transfer**
  Bidirectional between bonder and local workstation

- **Process data**
  Display of all process data of all connected wire bonders. Storage and data export in common formats

- **Data backup**
  Configuration of timed and regular data backup of all wire bonder data

- **RAW data view**
  Recorded PiQC quality values and sensor curves with filter options

- **Realtime view**
  Display of all quality values in real time

- **Teach score**
  Traceability of the teach procedures

- **Master programming**
  Load process programs directly from the PBS Server. Ensure that the wire bonders run only the latest released process programs

- **Multi Server**
  Run multiple PBS servers and administrate all with the Workbench in your office

Your benefits in the spotlight

Wire Bonder Server for PBS & PiQC

- Line management
- User management
- File transfer
- Process data
- Data backup
- RAW data view
- Realtime view
- Teach score
- Master programming
- Multi Server
New features of Workbench 2.0

Display of material consumption
- Early material consumption indicator (e.g., replace wire spool) or maintenance (e.g., wedge change)

PiQC data and visualization
- Central PiQC data storage of all bonders on the PBS server
- PiQC data comparison of different bonders
- New views:
  - Realtime view: Display of all quality values in real time
  - RAW data view: Recorded PiQC quality values

Remote PR assistance:
- Pattern recognition errors appearing on the bonder are displayed in the line management with a red camera icon and can be corrected remotely. The camera image represents the current position on the bonder surface. Manual adjustment can correct the error. With the options Skip or Skip part the faulty component can be skipped.
- Installation takes place as an additional option on the PBS computer.

You want more?
Contact us - we will provide a solution!
Hesse GmbH - Your partner for ultrasonic and thermosonic wire bonders for all common wire dimensions in combination with standardized or customized automation solutions.

Hesse GmbH, founded in 1995 and based in Paderborn, Germany, develops and manufactures fully automatic ultrasonic and thermosonic wire bonders together with standard or customer-specific automation solutions for the semiconductor industry backend. Hesse GmbH is one of the world’s leading producers of wire bonders using the ultrasonic wedge-wedge technology and develops customer-specific production processes.

All relevant semiconductor manufacturers are among the worldwide clientel of Hesse GmbH. Distribution and service are performed from the headquarters or by subsidiaries in Hong Kong, the US and Japan and together with partners in over 30 other countries.

The core competencies of the company are mechatronic systems, ultrasonic technology, control engineering and the detailed understanding and knowledge of the processes and physical effects relevant in ultrasonic joining technology. In order to maintain and expand technological leadership, we conduct intensive research and development in all aforementioned areas.

Process support, development and consulting:
We support you in developing and implementing your individual process requirements. Our range of services includes:
- Sample bonding
- Pre-production prototype
- Design validation builds
- Small series production
- Module production
- Process optimization

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